Material Declaration Report

Package Type:	SSOP 48L (300mil)
Pericom Package Code:	V48(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	657.500
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
			Silica Fused	60676-86-0	90.800	430.6531
MOLD COMPOUND	474.288	OSE	Epoxy Resin 1	Proprietary	3.000	14.2286
			Phenolic Resin	Proprietary	3.000	14.2286
			Epoxy Resin 2	Proprietary	2.000	9.4858
			Aromatic Phosphate	Proprietary	1.000	4.7429
			Carbon Black	1333-86-4	0.200	0.9486
		SPEL	Silica Fused	60676-86-0	88.000	417.3731
			Epoxy Resin	Proprietary	5.000	23.7144
			Phenolic Resin	Proprietary	4.500	21.3429
			Epoxy, Cresol Novolac	29690-82-2	2.000	9.4858
			Carbon Black	1333-86-4	0.500	2.3714
			Copper	7440-50-8	97.021	167.1903
LEADFRAME	172.324		Iron	7439-89-6	2.350	4.0496
			Silver	7440-22-4	0.453	0.7811
			Zinc	7440-66-6	0.111	0.1909
			Phosphorus	7723-14-0	0.065	0.1120
SILICON DIE	3.228		Silicon (Si)	7440-21-3	99.192	3.2022
			Non-hazardous Metal	Proprietary	0.808	0.0261
			Silver	7440-22-4	76.000	0.3748
DIE ATTACH EPOXY	0.493	OSE	Acrylic Resin	Proprietary	8.000	0.0394
			Acrylate	Proprietary	5.500	0.0271
			Polybutadiene derivative	Proprietary	5.500	0.0271
			Epoxy resin	Proprietary	2.500	0.0123
			Additive	Proprietary	1.000	0.0049
			Silver	7440-22-4	80.000	0.3945
		SPEL	Epoxy Resin	9003-36-5	10.000	0.0493
			Diluent	26447-14-3	6.000	0.0296
			Hardener	620-92-8	3.250	0.0160
			Dicyandamide	461-58-5	0.750	0.0037
GOLD WIRE	0.631		Gold(Au)	7440-57-5	99.990	0.6311
			Impurities	-	0.010	0.0001
SOLDER PLATING	6.542		Tin (Sn)	7440-31-5	99.990	6.5414
			Impurity	-	0.010	0.0007

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
Device	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.